

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE
FOR REFLOW SOLDERINGAMENDMENTAssistant Commissioner for Patents
Washington, D.C. 20231OFFICIAL
FAX RECEIVED
FEB 04 2002
GROUP 1700

Dear Sir:

In response to the Official Action mailed on November 2, 2001, the period for responding to which extends through February 4, 2002, the Applicants request that the present application be amended as shown below.

IN THE CLAIMS:

Please rewrite the following claims as shown below. A marked-up version of the amended claims is found on Attachment A at the end of this amendment.

*** ACTIVITY REPORT ***

RECEPTION OK

TX/RX NO.

6334

CONNECTION TEL

3015876623

CONNECTION ID

M TOBIAS

START TIME

02/04 17:51

USAGE TIME

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RESULT

OK